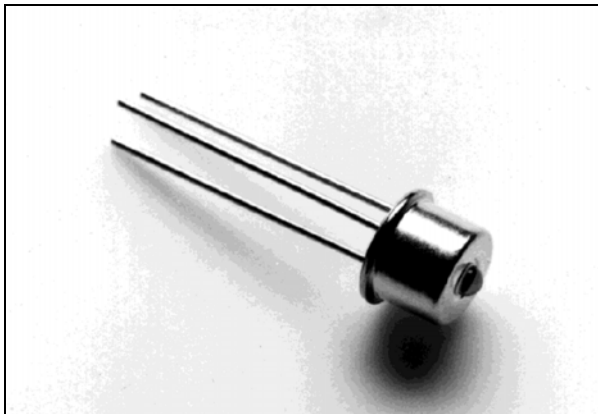


October 2004



Ordering Information

MF272	TO-46 Package
MF272 ST	ST Housing
MF272 SMA	SMA Housing
MF272 FC	FC Housing

-55°C to +125°C

Note: Rated Fiber coupled power apply only on the TO-46 package, for housing options fiber coupled power is typically 10% less

Features

- 810 nm Surface-Emitting LED
- 70 MHz Bandwidth
- Designed for 200/280 μ m fiber

Applications

- Avionics
- Sensors
- Military LANs

Description

This high speed device is optimized at 810 nm wavelength which is of particular interest for use in radiation-hardened fiber. It operates in a wide temperature range and delivers very high power to 200 μ m core fiber, making it ideal in avionics and military datacom applications.

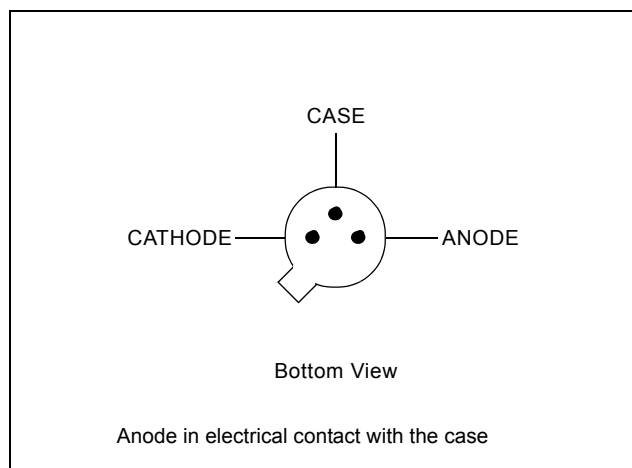


Figure 1 - Pin Diagram

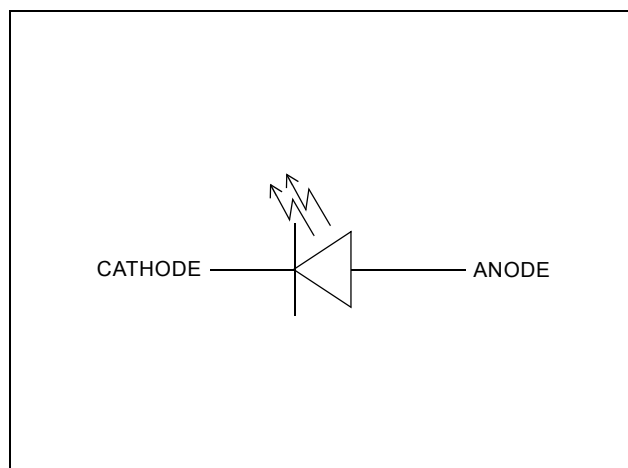


Figure 2 - Functional Schematic

Optical and Electrical Characteristics - Case Temperature 25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	
Fiber-Coupled Power (Figures 3, 4, and 5) (Table 1)	P _{fiber}	1300	1600		μW	I _F = 100 mA (Note 1)	Fiber: 200/280 μm Step Index
Rise and Fall Time (10-90%)	t _r ,t _f		7	10	ns	I _F = 100 mA (no bias)	
Bandwidth (3 dB _{el})	f _c		70		MHz	I _F = 100 mA	
Peak Wavelength	λ _p	790	810	830	nm	I _F = 100 mA	
Spectral Width (FWHM)	Δλ		50		nm	I _F = 100 mA	
Forward Voltage (Figure 7)	V _F		2.2	2.4	V	I _F = 100 mA	
Reverse Current	I _R			20	μA	V _R = 1 V	
Capacitance	C		250		pF	V _R =0V, f = 1 MHz	

Note 1: Measured at the exit of 100 meters of fiber.

Absolute Maximum Ratings

Parameter	Symbol	Limit
Storage Temperature	T_{stg}	-55 to +125°C
Operating Temperature (derating: Figure 6)	T_{op}	-55 to +125°C
Electrical Power Dissipation (derating: Figure 6)	P_{tot}	250 mW
Continuous Forward Current ($f < 10 \text{ kHz}$)	I_F	110 mA
Peak Forward Current (duty cycle $< 50\%$, $f > 1 \text{ MHz}$)	I_{FRM}	180 mA
Reverse Voltage	V_R	1.5 V
Soldering Temperature (2 mm from the case for 10 sec.)	T_{sld}	260°C

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance - Infinite Heat Sink	R_{thjc}			100	°C/W
Thermal Resistance - No Heat Sink	R_{thja}			400	°C/W
Temperature Coefficient - Optical Power	dP/dT_j		-0.4		%/°C
Temperature Coefficient - Wavelength	$d\lambda/dT_j$		0.3		nm/°C

Typical Fiber-Coupled Power

Core Diameter/Cladding Diameter Numerical Aperture					
50/125 μm 0.20	62.5/125 μm 0.275	100/140 μm 0.29	200/230 μm 0.37	200/280 μm 0.24	
60 μW	150 μW	600 μW	2000 μW	1600 μW	

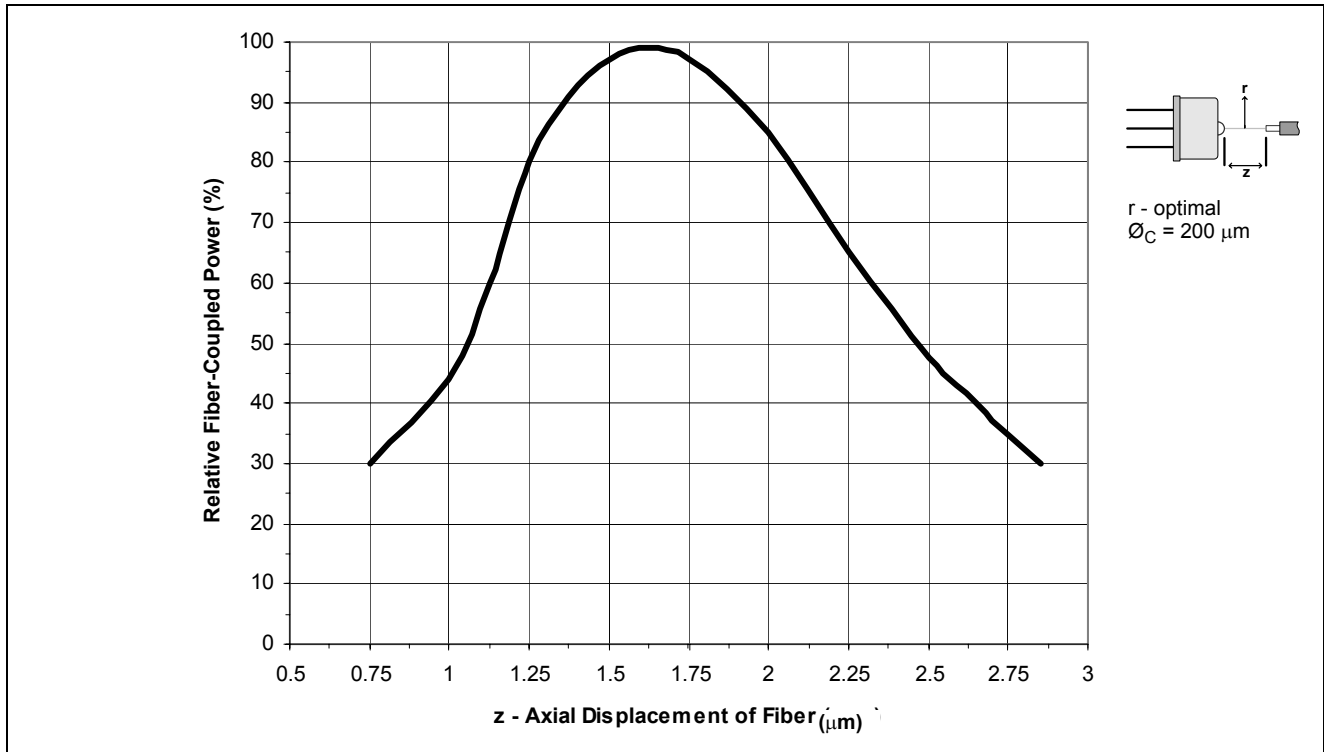


Figure 3 - Relative Fiber-coupled Power vs. z - Axial Displacement of Fiber

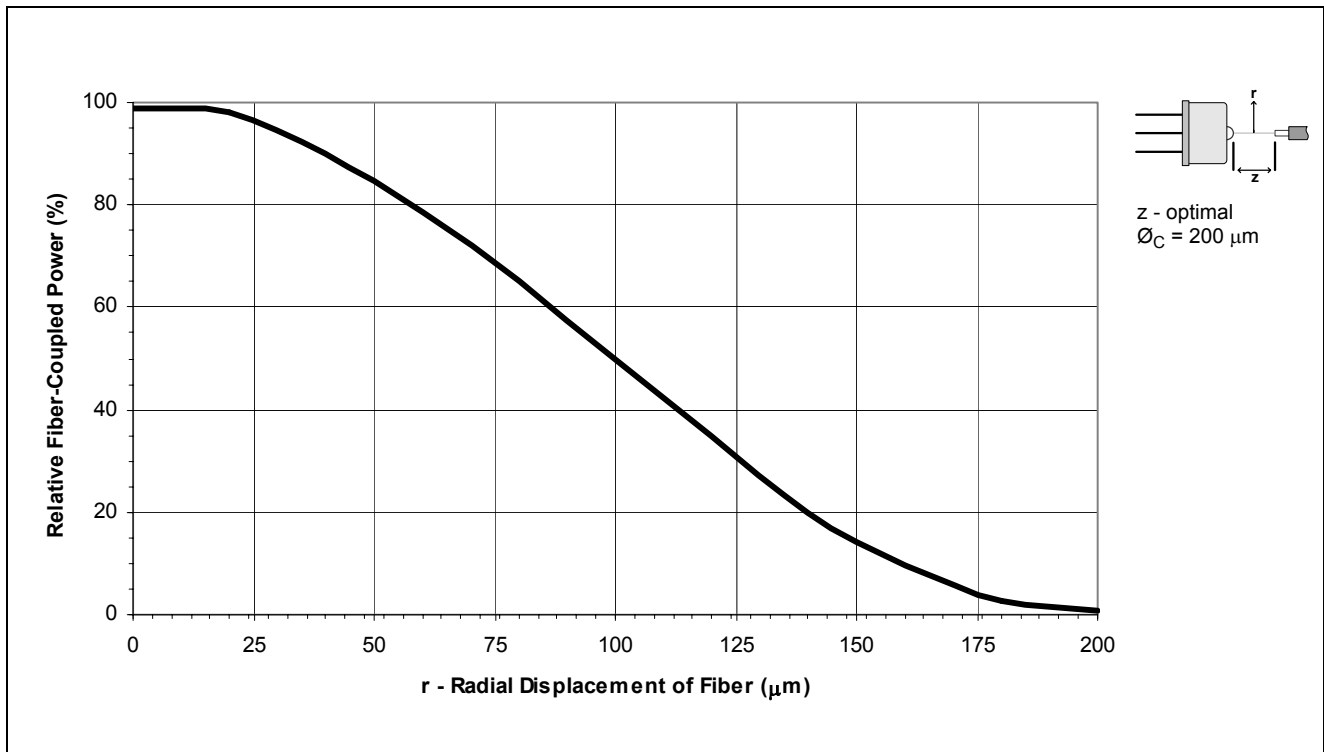


Figure 4 - Relative Fiber-Coupled Power vs. r - Radial Displacement of Fiber

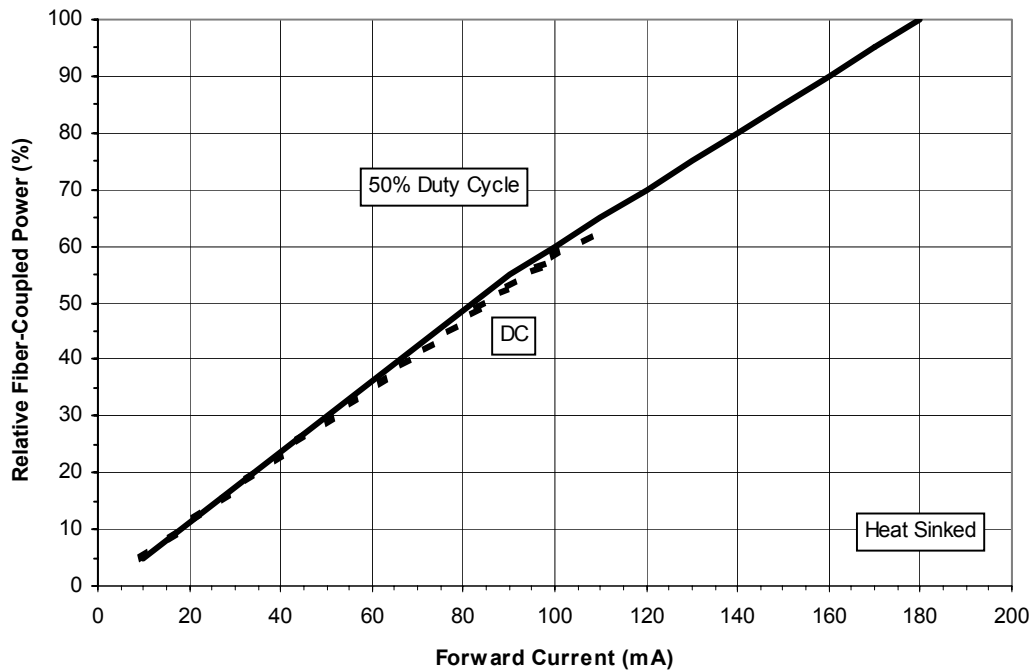


Figure 5 - Relative Fiber-coupled Power vs. Forward Current

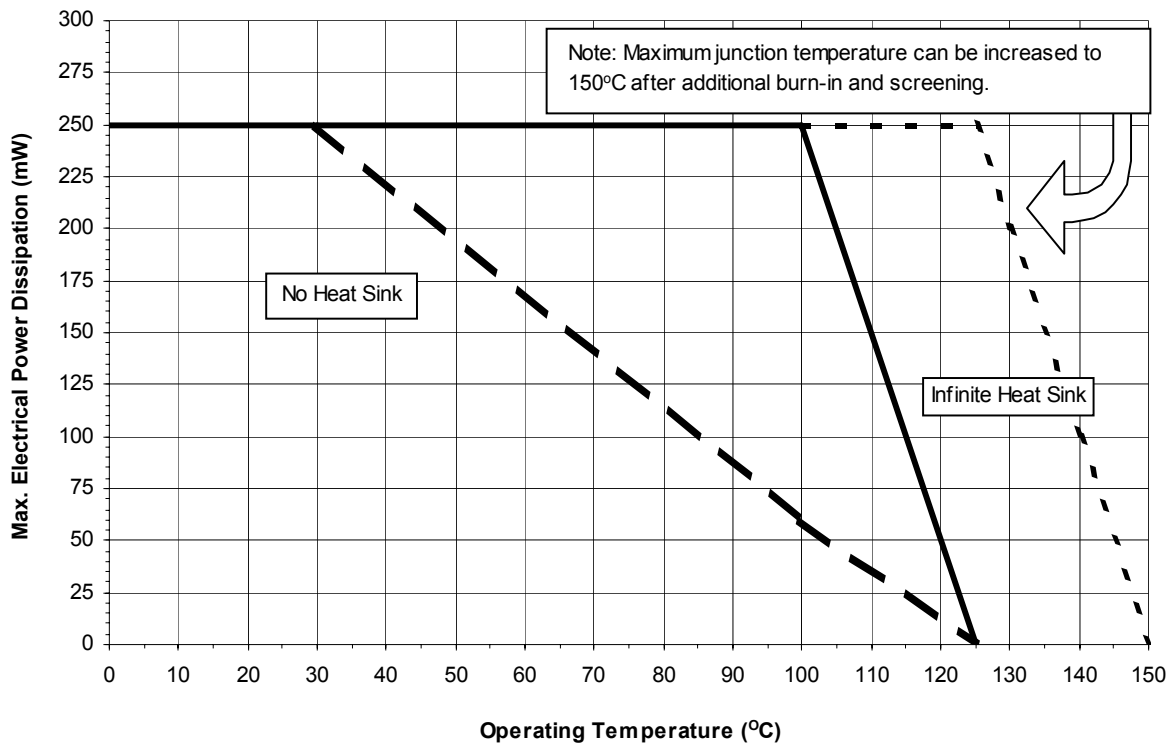
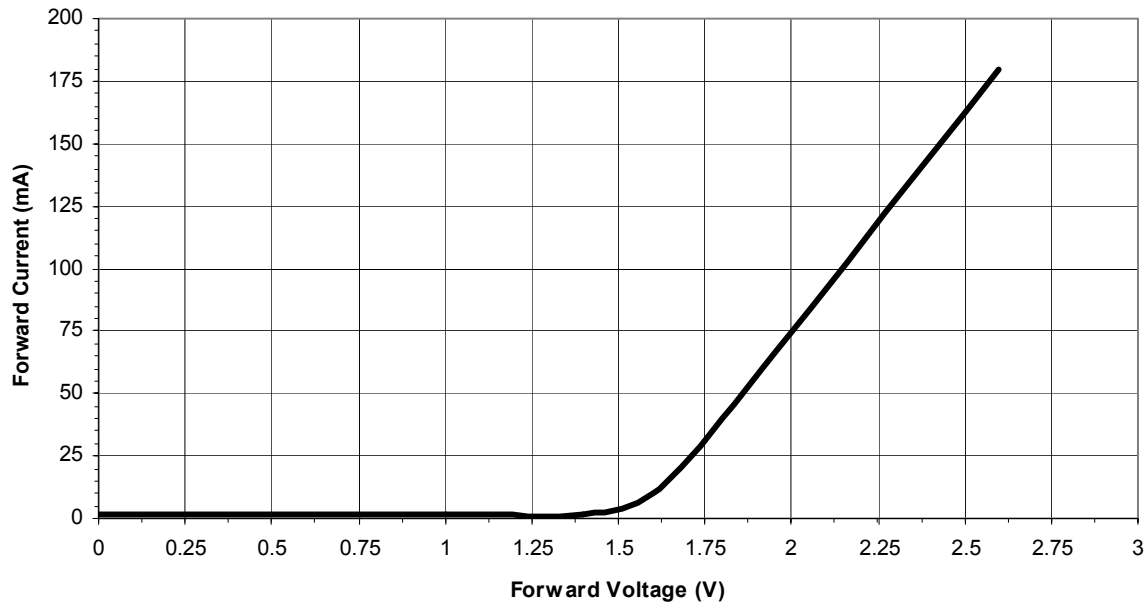
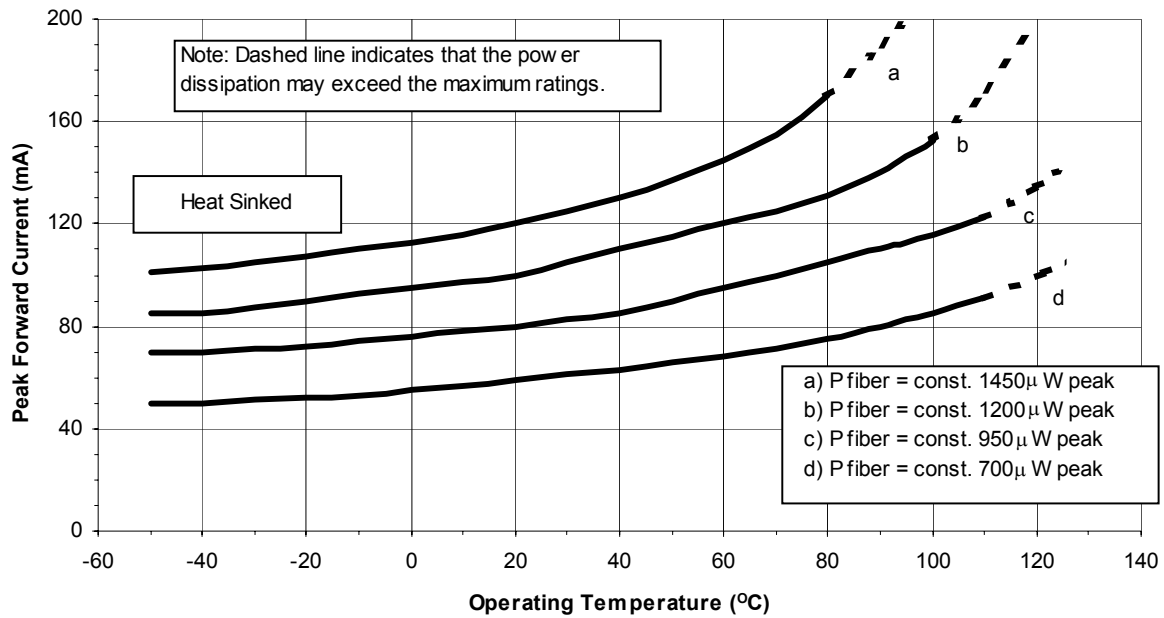


Figure 6 - Max. Electrical Power Dissipation vs. Operating Temperature

**Figure 7 - Forward Current vs. Forward Voltage****Figure 8 - Peak Forward Current vs. Operating Temperature**



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